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Attorney's Docket No. 042390.P5832

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application for:

**Donald S. Gardner, et al.**

Serial No. 09/253,306

Filed: February 19, 1999

For: **INTERCONNECTION ALLOY FOR  
INTEGRATED CIRCUITS**

Examiner: Tran, T.

Art Unit: 2811

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Assistant Commissioner for Patents  
Washington, D.C. 20231

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

Dear Sir:

In response to the Office Action mailed September 23, 2002, in connection with the above referenced patent application, the Applicants respectfully request entry of the following amendments and request reconsideration in view of the following remarks.

**IN THE CLAIMS:**

Presented below is a new claim in clean unmarked form.

E! 22. (New) The interconnect of claim 4, wherein the aluminum-copper-titanium alloy has a resistance in the range of 2.8 to 3.1 micro Ohm-cm.

**REMARKS**

In response to the above-identified Office Action, Applicants amend the application and seek reconsideration thereof. In this response, Applicants add claim 22. No claims have been